

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A flip-chip mounting electronic component, comprising:

plural a plurality of terminals dotted on a mounting face; and

a plurality of conductors formed on said terminals,

wherein said conductors are being formed as remaining parts from growing formation and/or removal, all the sums of heights of said terminals and said conductors thereon are being substantially equal, and tips of said conductors have having a substantially flat face.

2. (Currently Amended) The flip-chip mounting electronic component according to

claim 1,

wherein each of said conductors have has a truncated cone or a truncated pyramid shape with a small tip.

3. (Currently Amended) An electronic component, comprising:

a circuit element and a plurality of terminals formed on a ceramic plate face; and conductors formed on said terminals,

wherein said conductors are being formed as remaining parts from growing formation and/or removal, all the sums of heights of said terminals and said conductors thereon are being substantially equal, and tips of said conductors have having a substantially flat face.

4. (Currently Amended) The electronic component according to claim 3,
wherein each of said conductors have has a truncated cone or a truncated pyramid shape with a small tip.

5. (Currently Amended) The electronic component according to claim 3 or claim 4,
wherein said circuit element is a multiple or a network resistor or capacitor, or a network element composed of two or more elements selected from a capacitor, a resistor element and an inductor element.

6. (Currently Amended) A method for producing a flip-chip mounting electronic component having plural a plurality of terminals dotted on a mounting face and a plurality of conductors formed on the terminals, comprising the steps of:
coating the mounting face with a conductor having a predetermined thickness;
masking corresponding positions for the terminal parts on the conductor surface; and
removing the conductor except the mask parts, ~~wherein these steps are performed in this order the coating, masking and removing steps being carried out in the stated order.~~

7. (Currently Amended) A circuit board, comprising:

plural a plurality of flip-chip mounting lands dotted on a mounting face; and
a plurality of conductors formed on said terminals,
~~wherein~~ said conductors are being formed as remaining parts from growing formation
and/or removal, all the sums of heights of said lands and heights of said conductors thereon
are being substantially equal, and tips of said conductors have having a substantially flat face.

8. (Currently Amended) The circuit board according to claim 7,
wherein each of said conductors have has a truncated cone or a truncated pyramid
shape with a small tip.

9. (Currently Amended) A method for producing a circuit board having plural a
plurality of flip-chip mounting lands dotted on a mounting face, comprising the steps of:
coating the mounting face with a conductor having a predetermined thickness;
masking corresponding positions for the lands on the conductor surface; and
removing the conductor except the mask parts, ~~wherein these steps are performed in~~
~~this order the coating, masking and removing steps being carried out in the stated order.~~

10. (Original) A method for producing a package in which mounting face terminal
parts of a flip-chip mounting electronic component and/or flip-chip mounting lands of a
circuit board mounting face have conductors, the method comprising:
forming the conductors as remaining parts from growing formation and/or removal;
and

securing the conductors of the circuit board and the electronic component or the conductors of the electronic component and the circuit board with solder or anisotropic conductive material.

11. (Currently Amended) The method for producing a package according to claim 10,

wherein the conductors are constituted of copper and on surfaces thereof a nickel layer and a gold layer are formed in this the stated order, and said the securing step is realized carried out by fixing force of solder.